

Abstract of the Disclosure

The invention relates to a method for analysing connection conditions between an integrated circuit package and a
5 circuit board, wherein said integrated circuit package is electrically coupled to said circuit board by coupling elements, and therein said integrated circuit package is mechanically connected with said circuit board by support elements. To allow easy failure analysis, it is proposed
10 that physical values are picked-off from said support elements, and said physical values are evaluated to determine the condition of said connection between said integrated circuit package and said circuit board.

15 **For publication: figure 1.**